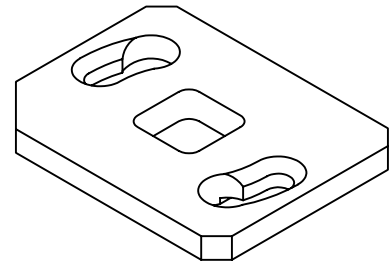
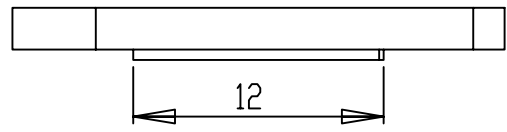
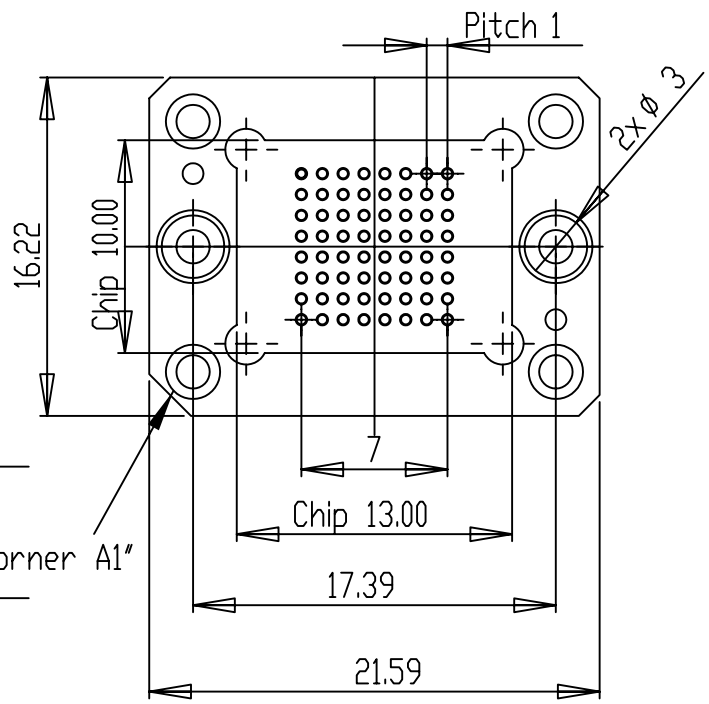
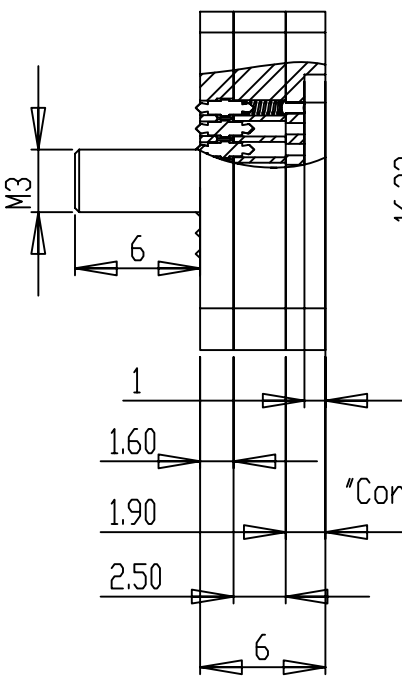
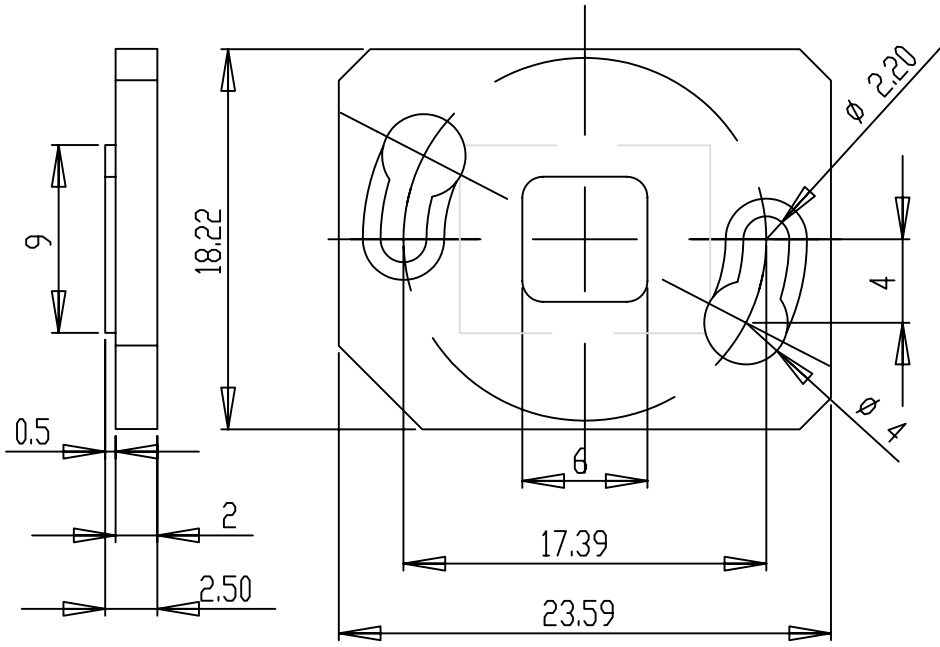


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	01/11/07	H.N.

SKT2843

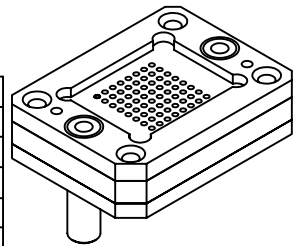
Retention frame  
Material: Epoxy FR4

Socket  
Material: TG 200

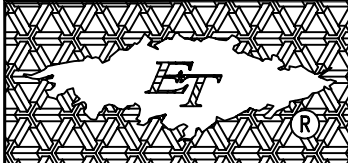


Recommended PCB layout  
for solderless socket  
4x PCB holes  $\phi 3.15 \pm 0.05$   
2x  $\phi 1.10 \pm 0.02$  (locating pegs)  
Gold plated pads  
 $\phi 0.60$  minimum

PACKAGE SPECIFICATIONS	
PIN COUNT	= 64
LEAD PITCH	= 1.00mm
GRID SIZE	= 8X8
PACKAGE SIZE	= 10.00X13.00mm
IC BALL DIA	= 0.70mm MAX
BALL HEIGHT	= 0.50mm MAX.



ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED



**Emulation Technology, Inc.**  
— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051  
TEL:(408)982-0660 FAX:(408)982-0664

GENERAL TOLERANCES:  $\pm 0.10$

SHEET: 1 OF 2	DATE: 01/11/07	REVISION: A	<b>ASSEMBLY DRAWING</b>
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: S-MBU-08-064SCA	
Scale N/A	DO NOT SCALE DRAWING	DESCRIPTION: BUP-064-3BG008A-90	

